

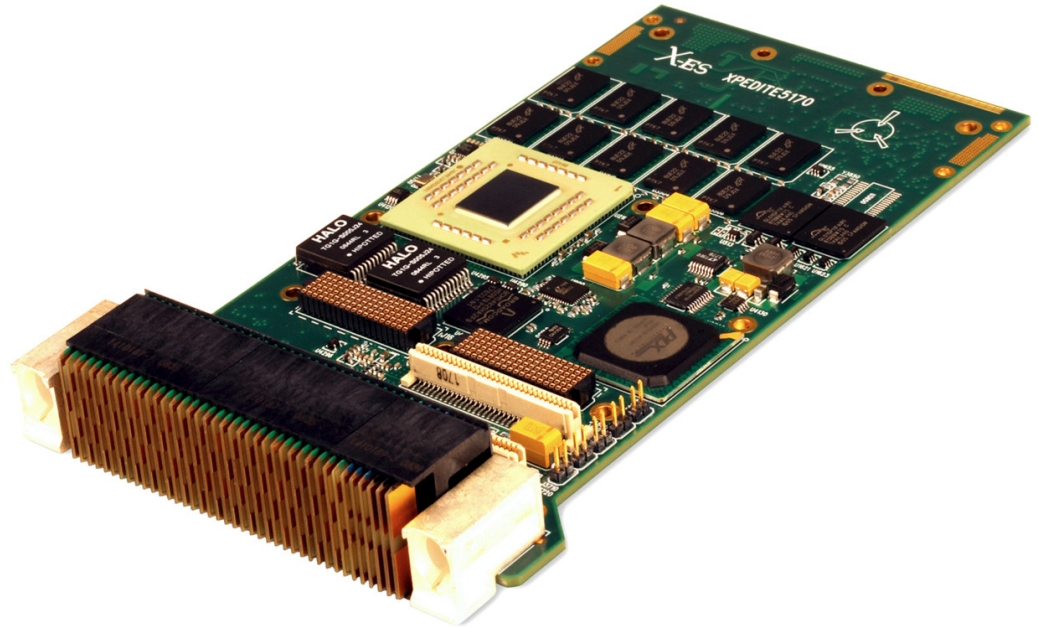
XPedite5170

End of Life

Dual-Core NXP MPC8640D Processor-Based Conduction- or Air-Cooled 3U VPX-REDI Module

Please see [XPedite5970](#)

- ▶ NXP MPC8640D processor with dual PowerPC e600 cores at up to 1.25 GHz
- ▶ 1 MB of L2 cache per core
- ▶ 3U VPX (VITA 46) module
- ▶ Ruggedized Enhanced Design Implementation (REDI)
- ▶ Conduction or air cooling
- ▶ Integrated AltiVec
- ▶ IEEE 754-compliant 64-bit Floating-Point Unit (FPU)
- ▶ Up to 4 GB (2 GB each) of up to DDR2-533 ECC SDRAM in two channels
- ▶ Up to 256 MB of NOR flash (with redundancy)
- ▶ Up to 4 GB of NAND flash
- ▶ XMC/PrPMC interface
- ▶ x4 PCI Express or serial RapidIO P1.A fabric interconnect
- ▶ x4 PCI Express P1.B fabric interconnect
- ▶ Two SerDes Gigabit Ethernet P1 fabric interconnects
- ▶ Two 10/100/1000BASE-T Ethernet ports (optional)
- ▶ Up to two RS-232/422/485 serial P2 ports
- ▶ Front I/O available via plugover module
- ▶ Green Hills INTEGRITY BSP
- ▶ Linux BSP
- ▶ Wind River VxWorks BSP
- ▶ QNX Neutrino BSP



XPedite5170

The XPedite5170 is a high-performance 3U VPX-REDI single board computer based on the NXP (formerly Freescale) MPC8640D processor. With dual PowerPC e600 cores running at up to 1.25 GHz, the MPC8640D delivers enhanced performance with AltiVec technology and IEEE 754 Dual-Precision Floating-Point and efficiency for today's network information processing and other embedded computing applications.

The XPedite5170 supports two separate channels of up to 2 GB each of up to DDR2-533 ECC SDRAM, as well as up to 4 GB of NAND flash and up to 256 MB of NOR flash (with redundancy). The XPedite5170 provides the option of utilizing a PCI Express or Serial RapidIO Fat Pipe P1 interconnect, as well as two SerDes Gigabit Ethernet Thin Pipe P1 fabric interconnects. The XPedite5170 also supports dual Gigabit Ethernet, GPIO, I²C, XMC I/O, PMC I/O, and up to two RS-232/422/485 serial ports through the P2 connector.

The XPedite5170 provides a ruggedized, high-performance, feature-rich solution to support the next generation of rugged embedded applications. Linux, Wind River VxWorks, QNX Neutrino, and Green Hills INTEGRITY Board Support Package (BSPs) are available.

X-ES

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Extreme Engineering Solutions

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Processor

- NXP (formerly Freescale) MPC8640D processor
- Dual PowerPC e600 cores at 1.067 to 1.25 GHz
- 1 MB of L2 cache per core
- Integrated AltiVec
- IEEE 754-compliant 64-bit FPU

Memory

- Up to 4 GB (2 GB each) of up to DDR2-533 ECC SDRAM in two channels
- Up to 256 MB of NOR flash (with redundancy)
- Up to 4 GB of NAND flash

VPX (VITA 46) P1 I/O

- x4 PCI Express or Serial RapidIO to P1.A
- x4 PCI Express to P1.B
- Two SerDes Gigabit Ethernet ports (or one 10/100/1000BASE-T port out P1 and one 10/100/1000BASE-T port out P2)
- X12d XMC P16 I/O

VPX (VITA 46) P2 I/O

- One 10/100/1000BASE-T port (when two SerDes Gigabit Ethernet P1 ports are not used)
- Up to two RS-232/422/485 serial ports
- I²C port
- 3.3 V GPIO signals
- P64s PMC P14 I/O

XMC/PrPMC Site

- 32-bit, 66 MHz PCI bus (PMC interface)
- x4 PCIe port (XMC interface)
- P64s P14 I/O support
- X12d P16 I/O support

Front Panel I/O

- Front panel RJ-45 Ethernet and micro-DB-9 RS-232 serial ports available via optional plugover module

Software

- Green Hills INTEGRITY BSP
- Linux BSP
- Wind River VxWorks BSP
- QNX Neutrino BSP

Physical Characteristics

- 3U VPX-REDI conduction- or air-cooled form factor
- Dimensions: 100 mm x 160 mm
- 0.8 in. pitch without solder-side cover
- 0.85 in. and 1.0 in. pitch with solder-side cover

Environmental Requirements

Contact factory for appropriate board configuration based on environmental requirements.

- Supported ruggedization levels (see chart below): 1, 3, 5
- Conformal coating available as an ordering option

Power Requirements

- MPC8640D at 1.067 GHz, DDR2-533, all interfaces active
- 30 W per board

Ruggedization Level	Level 1	Level 3	Level 5
Cooling Method	Standard Air-Cooled	Rugged Air-Cooled	Conduction-Cooled
Operating Temperature	0 to +55°C ambient (300 LFM)	-40 to +70°C (600 LFM)	-40 to +85°C (board rail surface)
Storage Temperature	-40 to +85°C ambient	-55 to +105°C ambient	-55 to +105°C (maximum)
Vibration	0.002 g ² /Hz (maximum), 5 to 2000 Hz	0.04 g ² /Hz (maximum), 5 to 2000 Hz	0.1 g ² /Hz (maximum), 5 to 2000 Hz
Shock	20 g, 11 ms sawtooth	30 g, 11 ms sawtooth	40 g, 11 ms sawtooth
Humidity	0% to 95% non-condensing	0% to 95% non-condensing	0% to 95% non-condensing

